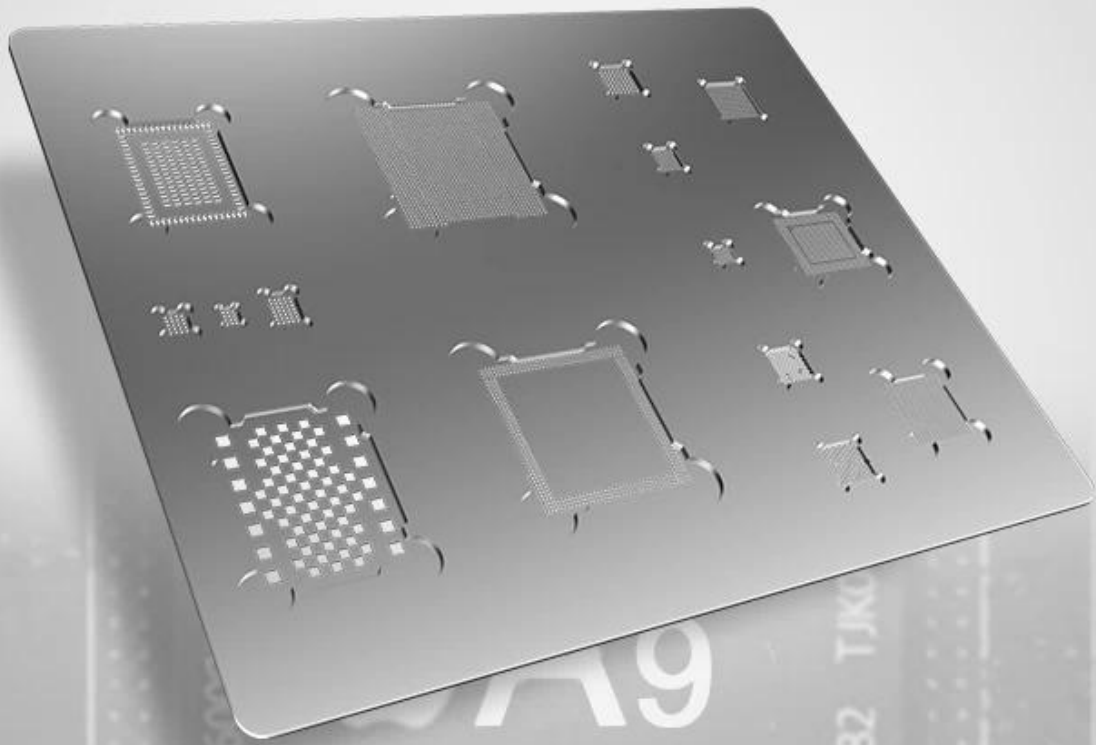


**BEST-A9-High** BGA IC S Tencils Reballing **iphone 6 6**

1x BGA Reballing iPhone 6s Plus

1x BGA Reballing iPhone 6s

# 3D GROOVE — REBALLING STENCIL —



SEMI-ETCHING PROCESS



COOLING HOLE DESIGN

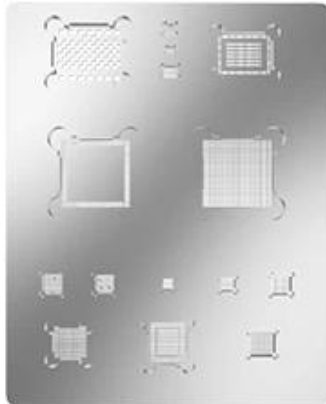


PRECISE ALIGNMENT



SQUARE HOLE

## Product Usage



MODEL	A9
WEIGHT	18.8g
MATERIAL	imported steel
SIZE	68.9 X 84.9mm
MATCHING MACHINE TYPE	iPhone6S/6SPlus

### ▼ CHARACTERISTICS

This product is used for BGA tinning repair of the iPhone 6S/6sPlus series. Imported steel, anti-rolling anti-deformation, automatic alignment, accurate hole position, non-stick tin, good toughness, good off-grid.

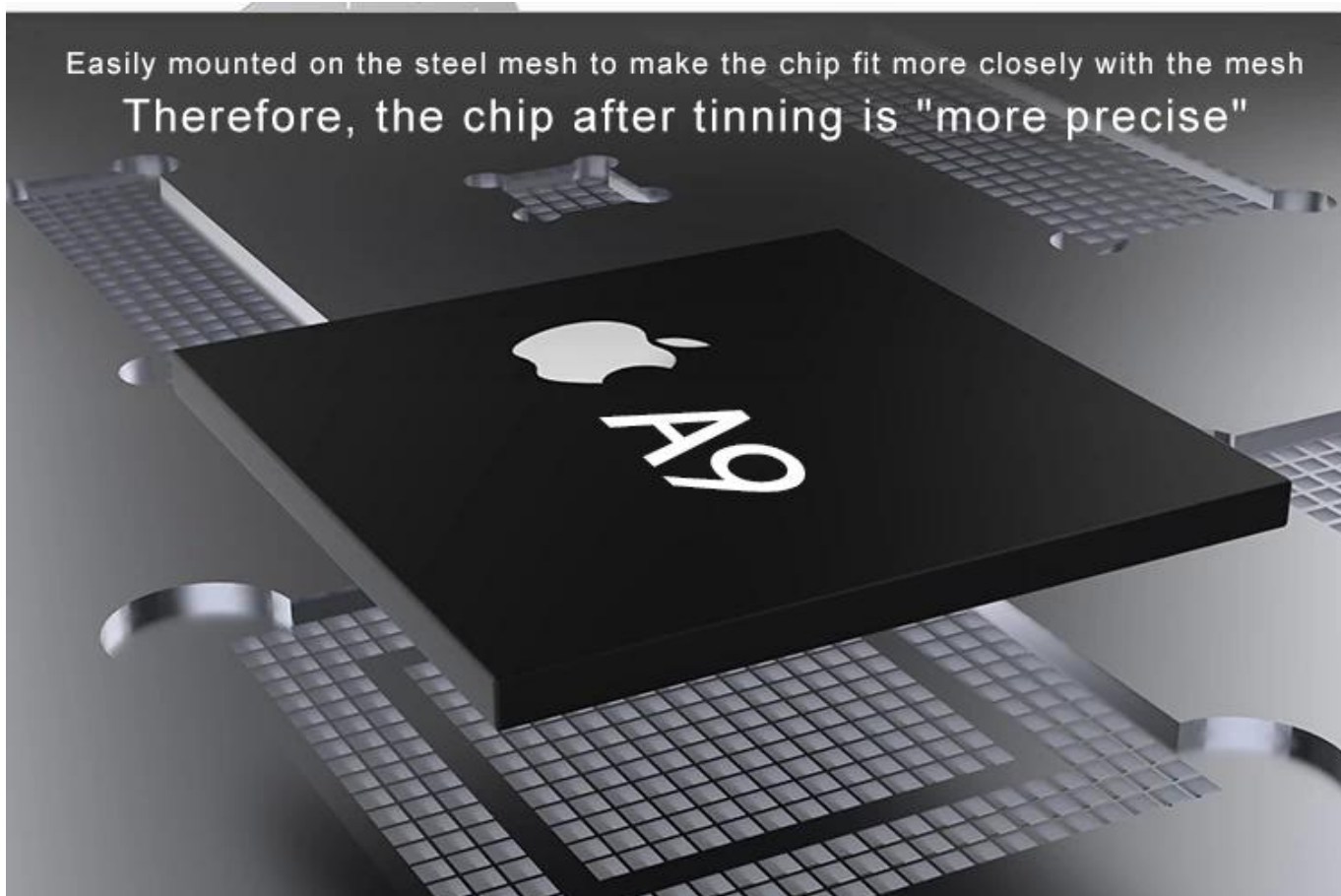
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IMPORTED STEEL

HIGH TOUGHNESS

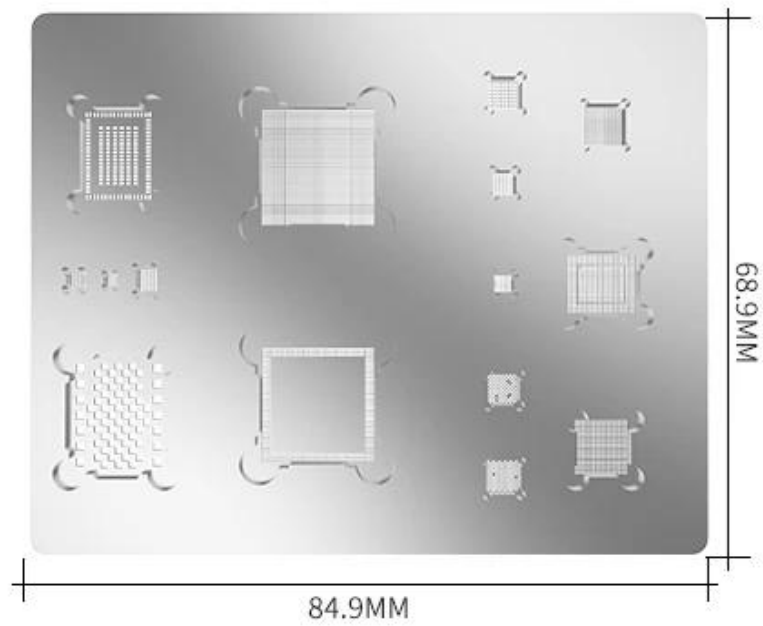


Easily mounted on the steel mesh to make the chip fit more closely with the mesh  
Therefore, the chip after tinning is "more precise"





## PRODUCT SIZE



Thin to 0.31mm

Precise die-casting **form heating**



